

# STARPOWER

SEMICONDUCTOR

**MOSFET**

## MD15FSR120L2SF

**1200V/15A 6 in one-package**

### General Description

STARPOWER MOSFET Power Module provides very low  $R_{DS(on)}$  as well as optimized intrinsic diode. It's designed for the applications such SMPS and solar power.

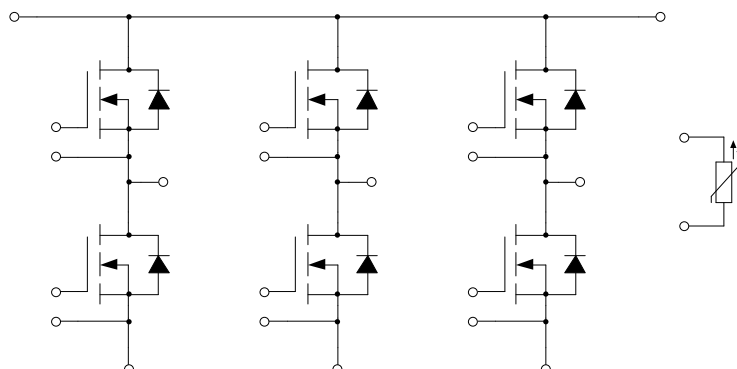
### Features

- SiC power MOSFET
- Low  $R_{DS(on)}$
- Optimized intrinsic reverse diode
- Avalanche ruggedness
- Low inductance case
- substrate for low thermal resistance
- Isolated heatsink using DBC technology

### Typical Applications

- Uninterruptible power supply
- Solar Power
- Switching mode power supply

### Equivalent Circuit Schematic



**Absolute Maximum Ratings**  $T_C=25^{\circ}\text{C}$  unless otherwise noted**MOSFET**

Symbol	Description	Value	Unit
$V_{DSS}$	Drain-Source Voltage	1200	V
$V_{GSS}$	Gate-Source Voltage	-4/+22	V
$I_D$	Drain Current @ $T_C=25^{\circ}\text{C}$ @ $T_C=100^{\circ}\text{C}$	23	A
		16	
$I_{DM}$	Pulsed Drain Current	52	A
$P_D$	Maximum Power Dissipation @ $T_j=175^{\circ}\text{C}$	98	W

**Inverse Diode**

Symbol	Description	Value	Unit
$I_S$	Source Current @ $T_C=100^{\circ}\text{C}$	TBD	A

**Module**

Symbol	Description	Value	Unit
$T_{jmax}$	Maximum Junction Temperature	175	$^{\circ}\text{C}$
$T_{jop}$	Operating Junction Temperature	-40 to +150	$^{\circ}\text{C}$
$T_{STG}$	Storage Temperature Range	-40 to +125	$^{\circ}\text{C}$
$V_{ISO}$	Isolation Voltage RMS, $f=50\text{Hz}$ , $t=1\text{min}$	2500	V

**MOSFET Characteristics**  $T_C=25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$R_{DS(on)}$	Static Drain-Source On-Resistance	$I_D=12\text{A}, V_{GS}=18\text{V}, T_j=25^\circ\text{C}$		62	78	$\text{m}\Omega$
		$I_D=12\text{A}, V_{GS}=18\text{V}, T_j=150^\circ\text{C}$		124		
$V_{GS(th)}$	Gate-Source Threshold Voltage	$I_D=6.45\text{mA}, V_{DS}=10\text{V}, T_j=25^\circ\text{C}$	2.8		4.8	V
$g_{fs}$	Forward Transconductance	$V_{DS}=10\text{V}, I_D=12\text{A}, T_j=25^\circ\text{C}$		8.3		S
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=V_{DSS}, V_{GS}=0\text{V}, T_j=25^\circ\text{C}$			80	$\mu\text{A}$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=V_{GSS}, V_{DS}=0\text{V}, T_j=25^\circ\text{C}$			100	nA
$R_{Gint}$	Internal Gate Resistance			4.0		$\Omega$
$C_{iss}$	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=800\text{V}, f=1.0\text{MHz}$		1498		pF
$C_{oss}$	Output Capacitance			45		pF
$C_{rss}$	Reverse Transfer Capacitance			3		pF
$Q_g$	Total Gate Charge	$I_D=12\text{A}, V_{DS}=800\text{V}, V_{GS}=18\text{V}$		64		nC
$Q_{gs}$	Gate-Source Charge			14		nC
$Q_{gd}$	Gate-Drain ("Miller") Charge			17		nC
$t_{d(on)}$	Turn-On Delay Time	$V_{DS}=800\text{V}, I_D=12\text{A}, R_G=0\Omega, V_{GS}=0/18\text{V}, T_j=25^\circ\text{C}$		4.4		ns
$t_r$	Rise Time			11		ns
$t_{d(off)}$	Turn-Off Delay Time			22		ns
$t_f$	Fall Time			10		ns
$E_{on}$	Turn-On Switching Loss	$V_{DS}=800\text{V}, I_D=12\text{A}, R_G=0\Omega, V_{GS}=0/18\text{V}, T_j=25^\circ\text{C}$		0.13		mJ
$E_{off}$	Turn-Off Switching Loss			0.01		mJ

**Inverse Diode Characteristics**  $T_C=25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit	
$V_F$	Diode Forward Voltage	$I_S=12\text{A}, V_{GS}=0\text{V}, T_j=25^\circ\text{C}$		3.3		V	
$t_{rr}$	Diode Reverse Recovery Time	$V_R=800\text{V}, I_S=12\text{A}, di/dt=3800\text{A}/\mu\text{s}, V_{GS}=0\text{V}, T_j=25^\circ\text{C}$		8.1		ns	
$Q_r$	Diode Reverse Recovery Charge				105		nC
$I_{rm}$	Peak Reverse Recovery Current				26		A

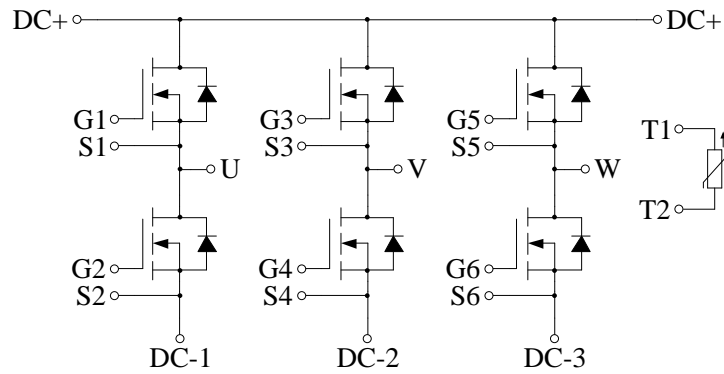
**NTC Characteristics**  $T_C=25^{\circ}\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$R_{25}$	Rated Resistance			5.0		$\text{k}\Omega$
$\Delta R/R$	Deviation of $R_{100}$	$T_C=100^{\circ}\text{C}, R_{100}=493.3\Omega$	-5		5	%
$P_{25}$	Power Dissipation				20.0	mW
$B_{25/50}$	B-value	$R_2=R_{25}\exp[B_{25/50}(1/T_2-1/(298.15\text{K}))]$		3375		K
$B_{25/80}$	B-value	$R_2=R_{25}\exp[B_{25/80}(1/T_2-1/(298.15\text{K}))]$		3411		K
$B_{25/100}$	B-value	$R_2=R_{25}\exp[B_{25/100}(1/T_2-1/(298.15\text{K}))]$		3433		K

**Module Characteristics**  $T_C=25^{\circ}\text{C}$  unless otherwise noted

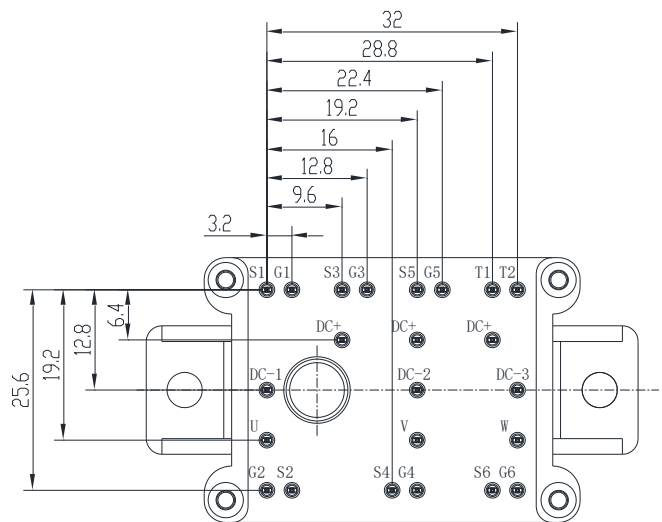
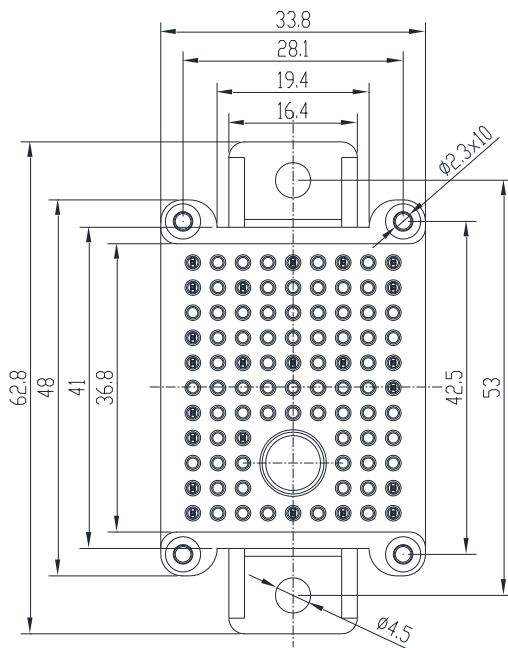
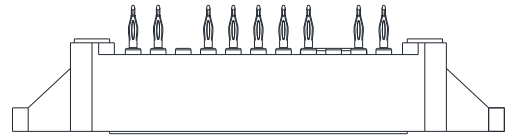
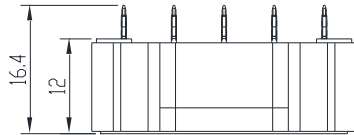
Symbol	Parameter	Min.	Typ.	Max.	Unit
$R_{thC}$	Junction-to-Case (per MOSFET)		1.384	1.522	$\text{K/W}$
$R_{thCH}$	Case-to-Heatsink (per MOSFET) Case-to-Heatsink (per Module)		0.348 0.058		$\text{K/W}$
F	Mounting Force Per Clamp	20		50	N.m
G	Weight of Module		24		g

**Circuit Schematic**



**Package Dimensions**

Dimensions in Millimeters



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